

Moongon Jung

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/11100138/publications.pdf>

Version: 2024-02-01

13
papers

291
citations

1684188
5
h-index

1872680
6
g-index

13
all docs

13
docs citations

13
times ranked

261
citing authors

#	ARTICLE	IF	CITATIONS
1	TSV stress-aware full-chip mechanical reliability analysis and optimization for 3D IC. Communications of the ACM, 2014, 57, 107-115.	4.5	57
2	Design and Analysis of 3D-MAPS (3D Massively Parallel Processor with Stacked Memory). IEEE Transactions on Computers, 2015, 64, 112-125.	3.4	52
3	TSV Stress-Aware Full-Chip Mechanical Reliability Analysis and Optimization for 3-D IC. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2012, 31, 1194-1207.	2.7	44
4	A study of IR-drop noise issues in 3D ICs with through-silicon-vias. , 2010, , .		27
5	Design for manufacturability and reliability for TSV-based 3D ICs. , 2012, , .		24
6	Impact of size effects in local interconnects for future technology nodes: A study based on full-chip layouts. , 2014, , .		23
7	Chip/package co-analysis of thermo-mechanical stress and reliability in TSV-based 3D ICs. , 2012, , .		14
8	Chip/Package Mechanical Stress Impact on 3-D IC Reliability and Mobility Variations. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2013, 32, 1694-1707.	2.7	12
9	Evaluating Chip-Level Impact of Cu/Low- κ Performance Degradation on Circuit Performance at Future Technology Nodes. IEEE Transactions on Electron Devices, 2015, 62, 940-946.	3.0	12
10	A fast simulation framework for full-chip thermo-mechanical stress and reliability analysis of through-silicon-via based 3D ICs. , 2011, , .		11
11	A study of TSV variation impact on power supply noise. , 2011, , .		7
12	Block-level designs of die-to-wafer bonded 3D ICs and their design quality tradeoffs. , 2013, , .		4
13	Fine-Grained 3-D IC Partitioning Study With a Multicore Processor. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1393-1401.	2.5	4